

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT3411834

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
AKIRA OKABE	06/09/2015
MASANORI TANOGUCHI	06/02/2015
RECEIVING PARTY DATA	
Name:	EPICREW CORPORATION
Street Address:	147-40 MASURAGAHARA
City:	OMURA, NAGASAKI
State/Country:	JAPAN
Postal Code:	856-0022
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14645734
CORRESPONDENCE DATA	
Fax Number:	(650)305-3055
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	650-305-3050
Email:	info@gardkaslow.com
Correspondent Name:	GARD AND KASLOW LLP
Address Line 1:	4 MAIN STREET, SUITE 120
Address Line 4:	LOS ALTOS, CALIFORNIA 94022
ATTORNEY DOCKET NUMBER:	PA1306US
NAME OF SUBMITTER:	V. RANDALL GARD
SIGNATURE:	/V. Randall Gard/
DATE SIGNED:	06/24/2015
Total Attachments: 2	
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ASSIGNMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned, Akira Okabe and Masanori Tanoguchi do hereby sell, assign, and transfer to Epicrew Corporation, a corporation with offices at 147-40 Masuragahara, Omura, Nagasaki, Japan 856-0022 ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the United States patent application filed on March 12, 2015 as US Application No. 14/645,734 and entitled:

**"SEMICONDUCTOR WAFER POSITION DISPLAY SYSTEM, SEMICONDUCTOR
WAFER POSITION DISPLAY METHOD, AND SEMICONDUCTOR WAFER
POSITION DISPLAY PROGRAM"**

and in and to said application and all utility, divisional, continuing, substitute, renewal, reissue, and all other patent applications which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be issued in the United States and all foreign countries on said improvements; and in and to all rights of priority resulting from the filing of said United States patent application; and

Agree that said Assignee may apply for and receive patents for said improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all

said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Date:

6/9/2015

Name:

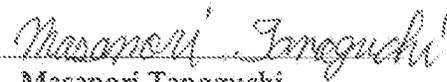


Akira Okabe

Date:

6/2/2015

Name:



Masanori Tanoguchi